typically 350µA.

PC Motherboards

Modems

packages.

M/XI/M ±15kV ESD-Protected, Quad, Low-Power RS-232 Line Receiver

General Description

The MAX1489E guad, low-power line receiver is

designed for EIA/TIA-232, EIA/TIA-562, and CCITT V.28

communications in harsh environments. Each receiver

input is protected against ±15kV electrostatic dis-

charge (ESD) shocks. These inputs have a ±25V range

and feature hysteresis and time-domain filtering. The outputs are TTL and CMOS compatible. The MAX1489E

has a 120kbps guaranteed data rate. Supply current is

The MAX1489E is pin compatible with the MC1489, MC14C89, SN75189, SN75C189, DS1489, and

DS14C89. It is available in 14-pin plastic DIP and SO

Interfacing Data Terminal Equipment (DTE) with Data Circuit-Terminating Equipment (DCE) Equipment Meeting IEC1000-4-2 (formerly IEC801-2) or ±15kV ESD Protection

Features

- Enhanced ESD Protection: ±15kV—Human Body Model ±8kV—IEC1000-4-2, Contact Discharge ±15kV—IEC1000-4-2, Air-Gap Discharge
- Latchup Free During an ESD Event
- Low 350µA Supply Current
- Input Hysteresis and Time-Domain Filtering Eliminate the Need for External Filtering
- Stable Input Thresholds
- Pin Compatible with MC1489, MC14C89, SN75189, SN75C189, DS1489, and DS14C89

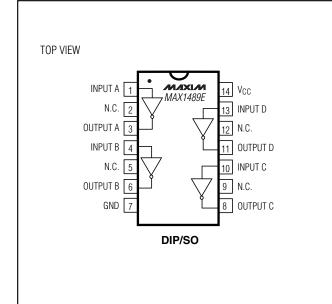
Ordering Information

PART	TEMP RANGE	PIN-PACKAGE
MAX1489ECPD	0°C to +70°C	14 Plastic DIP
MAX1489ECSD	0°C to +70°C	14 SO
MAX1489EC/D	0°C to +70°C	Dice*
MAX1489EEPD	-40°C to +85°C	14 Plastic DIP
MAX1489EESD	-40°C to +85°C	14 SO

* Dice are specified at $T_A = +25^{\circ}C$.

Pin Configuration

Maxim Integrated Products 1



MIXIM MIXIM *¹∕₄* MAX1488E ¹⁄4 MAX1489E TTL/CMOS TTL/CMOS INTERCONNECTING LOGIC LOGIC CABLE

SIGNAL GROUND

PC

MOTHERBOARD

(DTE)

MAXIM

¹⁄4 MAX1489E

=

For pricing, delivery, and ordering information, please contact Maxim/Dallas Direct! at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

Typical Operating Circuit

MAXIM 1⁄4 MAX1488E

MODEM

(DCE)

Applications

MAX1489E

ABSOLUTE MAXIMUM RATINGS

Supply Voltage (V _{CC})	+7V
Input Voltage (VIN)	±30V
Output Short-Circuit Current	
(Shorted to GND or V _{CC}) (Note 1)	Self Limiting
Continuous Power Dissipation ($T_A = +70^{\circ}C$)	
Plastic DIP (derate 10.00mW/°C above +70°C).	800mW
SO (derate 8.7mW/°C above +70°C)	695mW

Operating Temperature Ranges	
MAX1489EC_D	0°C to +70°C
MAX1489EE_D	40°C to +85°C
Storage Temperature Range	65°C to +160°C
Lead Temperature (soldering, 10s)	+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

(V_{CC} = 5V ±10%, T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at V_{CC} = 5V, T_A = +25°C.)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
DC CHARACTERISTICS							
Output Voltage High	Voh	$V_{IN} \le 0.4V$	I _{OUT} = -20μΑ	3.5	4.99		- V
			I _{OUT} = -3.2mA	2.5	4.41		
Output Voltage Low	Vol	V _{IN} ≥ 2.4V, I _{OUT} = 3.2mA			0.17	0.4	V
Output Short-Circuit Current	100	Shorted to GND		-35			
(Note 1)	los	Shorted to V _{CC}				60	mA
Supply Current	Icc				260	600	μA
Input Voltage Range	VIN			-25		25	V
Input Voltage High	VIH			1.60	2.17	2.60	V
Input Voltage Low	VIL			0.75	1.06	1.30	V
Input Hysteresis	V _{HYST}				1.11		V
Input Resistance	RIN			3.0	5.0	7.0	kΩ
TIMING CHARACTERISTICS	•			•			
Output Propagation Delay, Low to High	t _{PLH}	Figure 1		1.38		4.0	μs
Output Propagation Delay, High to Low	tphl	Figure 1		1.45		4.0	μs
Output Propagation Delay Skew, [tpLH - tpHL]	tskew	Figure 1			70		ns
Output Transition Time	t _{TR}	V _{OUT} = 10% to 90%			35	120	ns
Input Noise Rejection	t _N	Pulse amplitude =	5V (Note 2)		1.0		μs
Guaranteed Data Rate	DR			120	240		kbps
ESD CHARACTERISTICS	1	1		I			
		Human Body Moc	lel		±15		
ESD Protection		IEC1000-4-2 (Cor	tact Discharge)		±8		kV
		IEC1000-4-2 (Air-	Gap Discharge)		±15		1
	1						

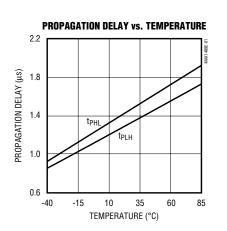
Note 1: Only one output may be shorted at a time.

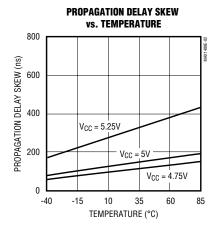
Note 2: See Noise Pulse Rejection graph in Typical Operating Characteristics section.

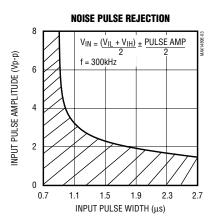


Typical Operating Characteristics

($V_{CC} = 5V$, $T_A = +25^{\circ}C$, unless otherwise noted.)







MAX1489E

Pin Description

PIN	NAME	FUNCTION
1, 4, 10, 13	INPUT_	Receiver Inputs
2, 5, 9, 12	N.C.	No Connect—not internally connected
3, 6, 8, 11	OUTPUT_	Receiver Outputs
7	GND	Ground
14	Vcc	Supply Voltage

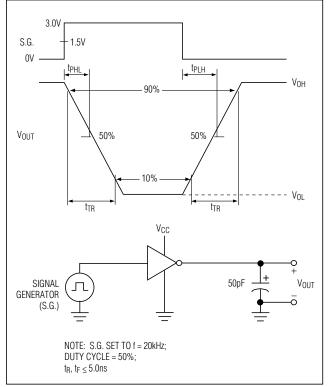


Figure 1. Timing Diagram

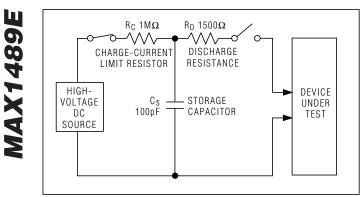


Figure 2a. Human Body ESD Test Model

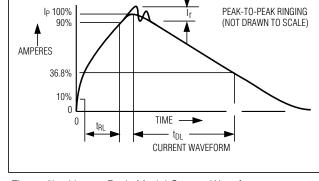


Figure 2b. Human Body Model Current Waveform

Human Body Model

Figure 2a shows the Human Body Model, and Figure 2b shows the current waveform it generates when discharged into a low impedance. This model consists of a 100pF capacitor charged to the ESD voltage of interest, which is then discharged into the test device through a $1.5k\Omega$ resistor.

IEC1000-4-2

The IEC100-4-2 standard covers ESD testing and performance of finished equipment; it does not specifically refer to integrated circuits. The MAX1489E helps you design equipment that meets Level 4 (the highest level) of IEC1000-4-2, without additional ESD protection components.

The major difference between tests done using the Human Body Model and IEC1000-4-2 is higher peak current in IEC1000-4-2. Because series resistance is lower in the IEC1000-4-2 ESD test model (Figure 3a), the ESD withstand voltage measured to this standard is generally lower than that measured using the Human Body Model. Figure 3b shows the current waveform for the ±8kV IEC1000-4-2 Level 4 ESD Contact Discharge test.

The Air-Gap test involves approaching the device with a charged probe. The Contact Discharge method connects the probe to the device before the probe is energized.

Detailed Description

±15kV ESD Protection

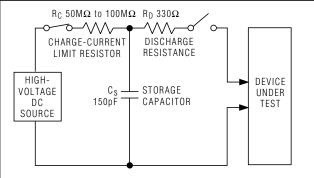
As with all Maxim devices, ESD protection structures are incorporated on all pins to protect against electrostatic discharges encountered during handling and assembly. The MAX1489E receiver inputs have extra protection against static electricity found in normal operation. Maxim's engineers developed state-of-theart structures to protect these pins against ESD of ± 15 kV without damage. After an ESD event, the MAX1489E keeps working without latchup.

ESD protection can be tested in various ways; the receiver inputs are characterized for protection to the following:

- 1) ±15kV using the Human Body Model
- 2) ±8kV using the Contact Discharge method specified in IEC1000-4-2 (formerly IEC801-2)
- ±15kV using the Air-Gap Discharge method specified in IEC1000-4-2 (formerly IEC801-2).

ESD Test Conditions

Contact Maxim for a reliability report that documents test setup, methodology, and results.



The Machine Model for ESD testing uses a 200pF stor-

age capacitor and zero-discharge resistance. Its objec-

tive is to mimic the stress caused by contact that

occurs with handling and assembly during manufactur-

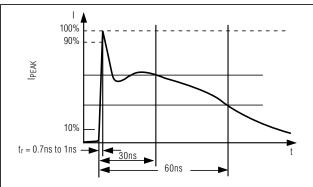
ing. Of course, all pins (not just RS-232 inputs and out-

puts) require this protection during manufacturing.

Therefore, the Machine Model is less relevant to the I/O

ports than the Human Body Model and IEC1000-4-2.

Figure 3a. IEC1000-4-2 ESD Test Model



MAX1489E

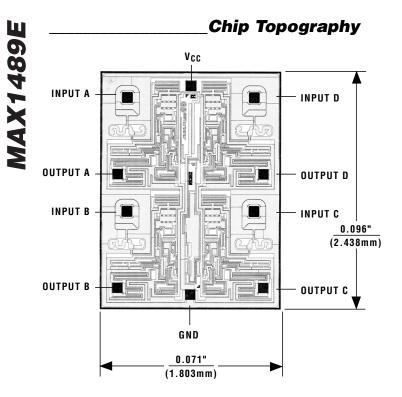
Figure 3b. IEC1000-4-2 ESD Generator Current Waveform

Applications Information

Use proper layout to ensure other devices on your board are not damaged in an ESD strike. Currents as high as 60A can instantaneously pass through the ground pin, so it is important to minimize the groundlead return path to the power supply. A separate return path to the power supply is recommended. Trace widths should be greater than 40 mils. V_{CC} must be bypassed with 0.1µF capacitors as close to the part as possible to ensure maximum ESD protection.

Machine Model

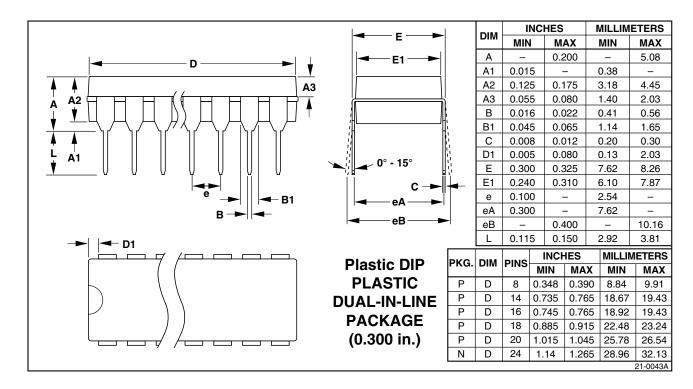
/N/XI/N



TRANSISTOR COUNT: 144 SUBSTRATE CONNECTED TO GND

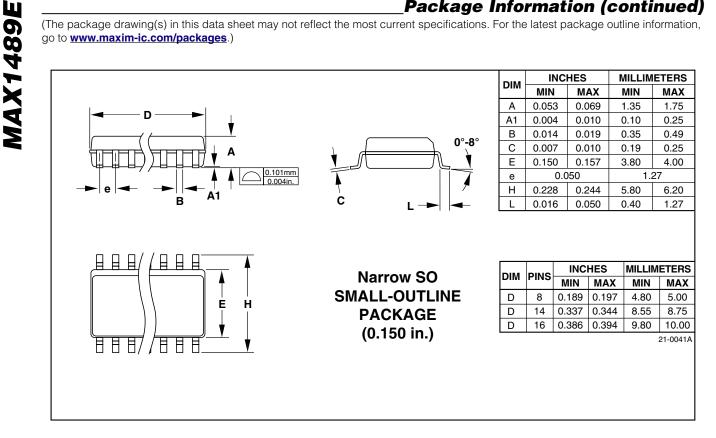
Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)



Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.)



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